

Title (en)  
ELECTRONIC COMPONENT AND PROCESS FOR PRODUCING SAME

Title (de)  
ELEKTRONISCHES BAUELEMENT UND VERFAHREN ZU SEINER HERSTELLUNG

Title (fr)  
COMPOSANT ELECTRONIQUE ET SON PROCEDE DE FABRICATION

Publication  
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Application  
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Abstract (en)  
[origin: DE4413529A1] An electronic component and a process for producing it are disclosed. The electronic component consists of a chip and a housing. A layer (3) of hot-melt-type adhesive is applied between the lower side (1a) of the chip (1) and the inner side (2a) of the bottom (2) of the housing. In order to produce such a component, a defined amount of hot-melt-type adhesive is applied on the predetermined connection between the chip and the housing, the chip is positioned thereon and pressed down. The thus prefabricated component is cooled and further processed. Once its processing is finished and its housing is closed, the complete component is heated once again, so that the hot-melt-type adhesive softens once again and resolidifies when the component is cooled. Mechanical stresses in the chip or between the chip and the housing are thus reduced.

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